

Appl. No. 10/690,431
Amdt. dated May 20, 2005
Reply to Office Action of Feb. 12, 2005

AMENDMENTS TO THE CLAIMS

Claims 1-13 were canceled in the Preliminary Amendment filed October 20, 2003 and claims 14-22 were presented.

Please amend claims 20, 21 and 22 as set forth in the following listing of the claims.

Claims 1-13 (canceled)

14. (previously presented) A planarized ultra fine particle film forming method for forming a planarized ultra fine particle film from a deposited film of ultra fine particles formed by supplying the ultra fine particles to a substrate, the method comprising a planarizing step of planarizing a surface of the deposited film of the ultra fine particles by blowing planarizing fine particles having a grinding/polishing function at an oblique incidence angle toward the surface of the deposited film.

15. (original) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles are accelerated by using an

electrostatic field or gas and blown toward the surface of the deposited film of the ultra fine patterns.

16. (original) A planarized ultra fine particle film forming method according to claim 14, wherein the incidence angle of a flow of the planarizing fine particles relative to the substrate is in a range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees.

17. (previously presented) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles have a same composition as that of the ultra fine particles.

18. (previously presented) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles have a particle diameter larger than that of the ultra fine particles.

19. (previously presented) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles have a rigidity higher than that of the ultra fine particles.

20. (currently amended) A planarized ultra fine particle film forming apparatus for forming a planarized ultra fine particle film from a deposited film of ultra fine particles, the planarized film forming apparatus comprising a substrate for holding a film, a nozzle for supplying ultra fine particles to the substrate to form a deposited film, and a spray apparatus that jets out planarizing fine particles towards the deposited film to planarize the film of formed by supplying the ultra fine particles to a on the substrate, wherein the planarizing fine particles having from the spray apparatus have a grinding/polishing function and are blown at an oblique incidence angle toward the surface of the deposited film.

21. (currently amended) A planarized ultra fine particle film forming apparatus according to claim 20, ~~further comprising a wherein said spray apparatus such as comprises a nozzle, and an electrostatic acceleration gun for jetting out, at the same time or separately, the ultra fine particles toward the substrate, and a center axis of a jet flow of said spray apparatus being is set in an incidence angle range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees relative to a surface of the substrate.~~

22. (currently amended) A planarized ultra fine particle film forming apparatus according to claim 20, ~~further comprising a wherein said spray apparatus such as comprises a nozzle, and an electrostatic acceleration gun for~~

jetting out, at the same time or separately, the ultra fine particles toward the substrate, and a flow of the ultra fine particles or planarizing particles jetted out from said spray apparatus ~~being~~ is set to have a conical shape having an incidence angle range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees about a center axis of a jet flow of said spray apparatus.